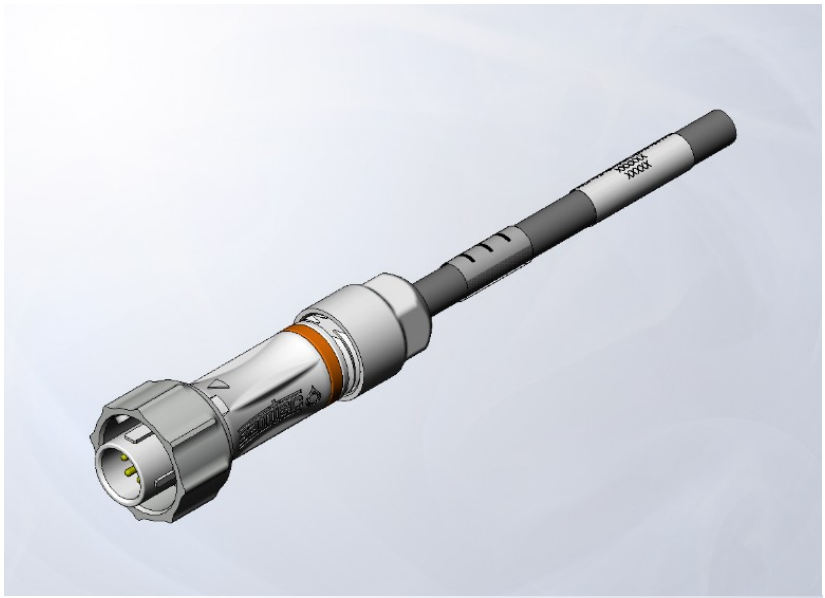
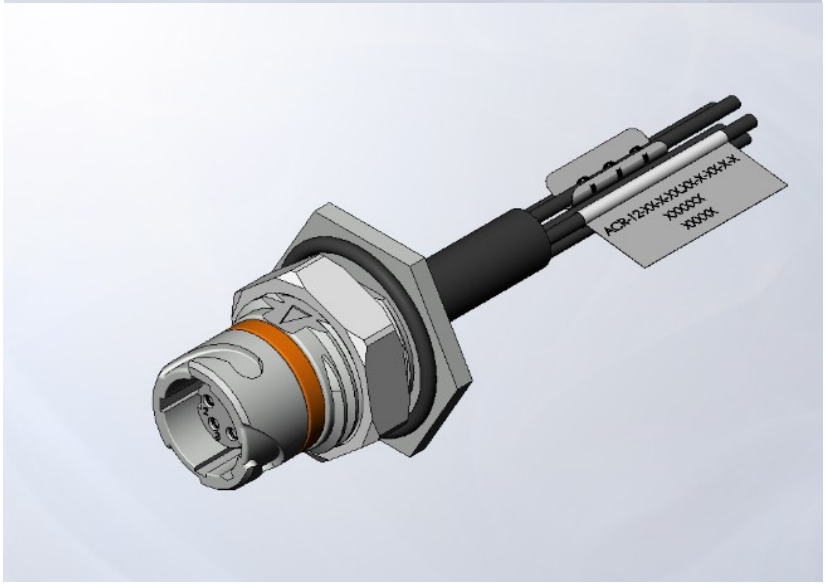
Project Number: Design Qualification Test Report	Tracking Code: 161626_Report_Rev_1			
Requested by: Travis Newton	Date: 8/22/2012	Product Rev: 0		
Part #: ACP-12-05-H-00.25-T-S-M-1\ ACR-12-05-H-00.25-S-S1-M-1	Lot #: N/A	Tech: Clay Taylor	Eng: Eric Mings	
Part description: ACP /ACR		Qty to test: 60		
Test Start:09/20/2011	Test Completed: 10/10/2011			





Design Qualification Test Report

ACP \ ACR
ACP-12-05-H-00.25-T-S-M-1\ ACR-12-05-H-00.25-S-S1-M-1

CERTIFICATION

All instruments and measuring equipment were calibrated to National Institute for Standards and Technology (NIST) traceable standards according to IS0 10012-l and ANSI/NCSL 2540-1, as applicable.

SCOPE

To perform the following tests: Design Qualification Test, Please see test plan.

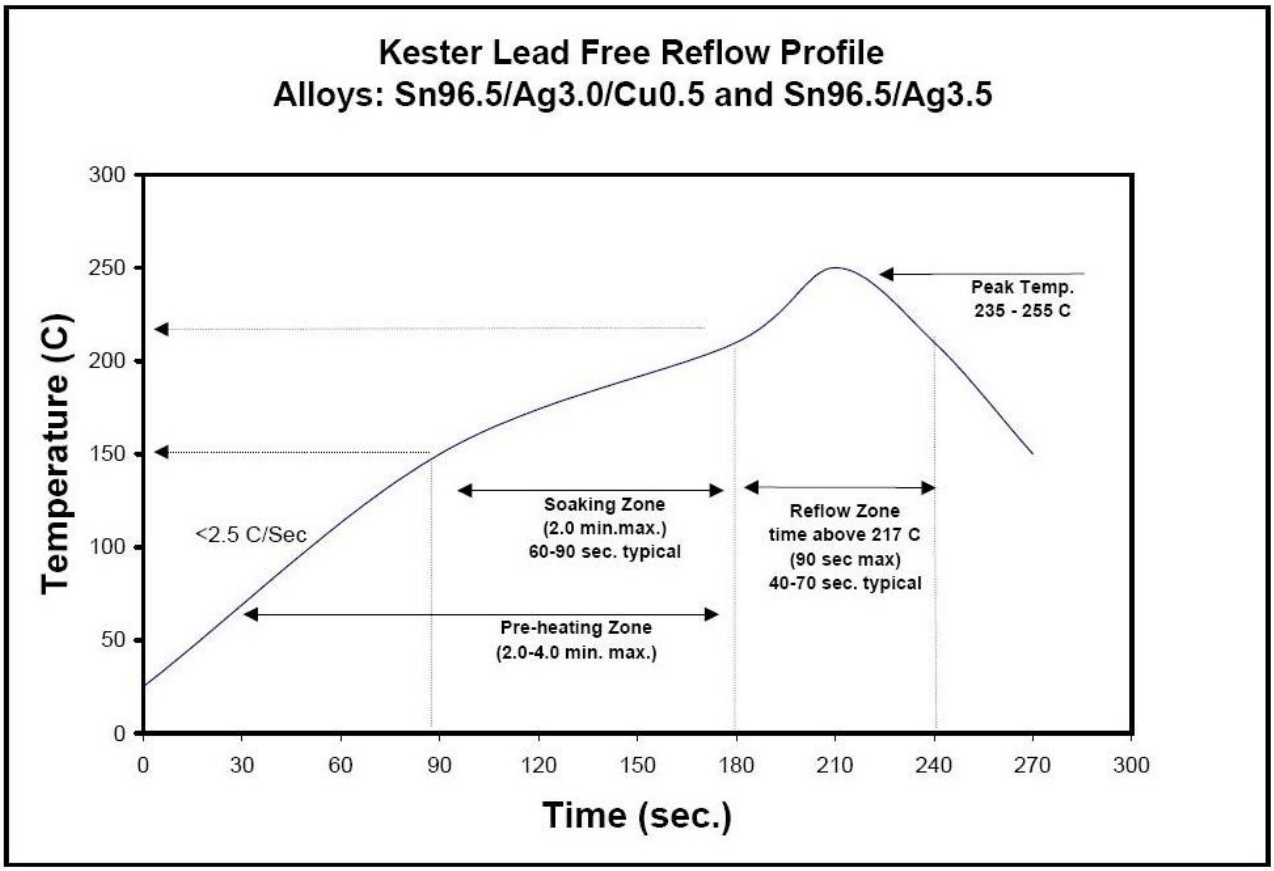
APPLICABLE DOCUMENTS

Standards: EIA Publication 364

TEST SAMPLES AND PREPARATION

1) All materials were manufactured in accordance with the applicable product specification.
2) All test samples were identified and encoded to maintain traceability throughout the test sequences.
3) After soldering, the parts to be used for LLCR and DWV/IR testing were cleaned according to TLWI-0001.
4) Either an automated cleaning procedure or an ultrasonic cleaning procedure may be used.
5) The automated procedure is used with aqueous compatible soldering materials.
6) Parts not intended for testing LLCR and DWV/IR are visually inspected and cleaned if necessary.
7) Any additional preparation will be noted in the individual test sequences.
8) Solder Information: Lead free
9) Re-Flow Time/Temp: See accompanying profile.
10) Samtec Test PCBs used: PCB-103219-TST-XX

TYPICAL OVEN PROFILE (Soldering Parts to Test Boards)



FLOWCHARTS

Durability/Mating/Unmating/Gaps

TEST STEP	GROUP A1 8 Assemblies
02	LLCR-1
03	Forces - Mating / Unmating
04	25 Cycles
05	Forces - Mating / Unmating
06	25 Cycles (50 Total)
07	Forces - Mating / Unmating
08	25 Cycles (75 Total)
09	Forces - Mating / Unmating
10	25 Cycles (100 Total)
11	Forces - Mating / Unmating
12	Clean w/Compressed Air
14	LLCR-2
15	Thermal Shock (Mated and Undisturbed)
16	LLCR-3
17	Cyclic Humidity (Mated and Undisturbed)
18	LLCR-4
19	Forces - Mating / Unmating

Thermal Shock = EIA-364-32, Table II, Test Condition I:

-55ºC to +85ºC 1/2 hour dwell, 100 cycles

Humidity = EIA-364-31, Test Condition B (240 Hours)

and Method III (+25°C to +65°C @ 90% RH to 98% RH)

ambient pre-condition and delete steps 7a and 7b

Mating / Unmating Forces = EIA-364-13

LLCR = EIA-364-23, LLCR

20 mV Max, 100 mA Max

Use Keithley 580 or 3706 in 4 wire dry circuit mode

FLOWCHARTS Continued

IR & DWV

TEST STEP	GROUP A1 2 Mated Sets Break Down Pin-to-Pin	GROUP A2 2 Unmated of Part # Being Tested Break Down Pin-to-Pin	GROUP A3 2 Unmated of Mating Part # Break Down Pin-to-Pin	GROUP B1 2 Mated Sets Pin-to-Pin
01	DWV/Break Down Voltage	DWV/Break Down Voltage	DWV/Break Down Voltage	IR & DWV at test voltage (on both mated sets and on each connector unmated)
02				Thermal Shock (Mated and Undisturbed)
03				IR & DWV at test voltage (on both mated sets and on each connector unmated)
04				Cyclic Humidity (Mated and Undisturbed)
05				IR & DWV at test voltage (on both mated sets and on each connector unmated)

DWV on Group B1 to be performed at Test Voltage

DWV test voltage is equal to 75% of the lowest break down voltage from Groups A1, A2 or A3

Thermal Shock = EIA-364-32, Table II, Test Condition I:

-55°C to +85°C 1/2 hour dwell, 100 cycles

Humidity = EIA-364-31, Test Condition B (240 Hours)

and Method III (+25°C to +65°C @ 90% RH to 98% RH)

ambient pre-condition and delete steps 7a and 7b

IR = EIA-364-21

DWV = EIA-364-20, Test Condition 1

Current Carrying Capacity - Array

TEST STEP	GROUP A1 3 Mated Assemblies All Contacts Powered
01	CCC

(TIN PLATING) - Tabulate calculated current at RT, 65°C, 75°C and 95°C

after derating 20% and based on 105°C

(GOLD PLATING) - Tabulate calculated current at RT, 85°C, 95°C and 115°C

after derating 20% and based on 125°C

CCC, Temp rise = EIA-364-70

ATTRIBUTE DEFINITIONS

The following is a brief, simplified description of attributes.

THERMAL SHOCK:

1) EIA-364-32, *Thermal Shock (Temperature Cycling) Test Procedure for Electrical Connectors.*
2) Test Condition 1: -55°C to +85°C
3) Test Time: ½ hour dwell at each temperature extreme
4) Number of Cycles: 100
5) All test samples are pre-conditioned at ambient.
6) All test samples are exposed to environmental stressing in the mated condition.

HUMIDITY:

1) Reference document: EIA-364-31, *Humidity Test Procedure for Electrical Connectors.*
2) Test Condition B, 240 Hours.
3) Method III, +25° C to + 65° C, 90% to 98% Relative Humidity excluding sub-cycles 7a and 7b.
4) All samples are pre-conditioned at ambient.
5) All test samples are exposed to environmental stressing in the mated condition.

MATING/UNMATING:

1) Reference document: EIA-364-13, *Mating and Unmating Forces Test Procedure for Electrical Connectors*.
2) The full insertion position was to within 0.003” to 0.004” of the plug bottoming out in the receptacle to prevent damage to the system under test.
3) One of the mating parts is secured to a floating X-Y table to prevent damage during cycling.

INSULATION RESISTANCE (IR):

To determine the resistance of insulation materials to leakage of current through or on the surface of these materials when a DC potential is applied.

1) PROCEDURE:
    a. Reference document: EIA-364-21, *Insulation Resistance Test Procedure for Electrical Connectors*.
    b. Test Conditions:
        i. Between Adjacent Contacts or Signal-to-Ground
        ii. Electrification Time 2.0 minutes
        iii. Test Voltage (500 VDC) corresponds to calibration settings for measuring resistances.
2) MEASUREMENTS:
    a. When the specified test voltage is applied (VDC), the insulation resistance shall not be less than 1000 megohms.

ATTRIBUTE DEFINITIONS

The following is a brief, simplified description of attributes.

DIELECTRIC WITHSTANDING VOLTAGE (DWV):

To determine if the sockets can operate at its rated voltage and withstand momentary over potentials due to switching, surges, and other similar phenomenon. Separate samples are used to evaluate the effect of environmental stresses so not to influence the readings from arcing that occurs during the measurement process.

1) PROCEDURE:
    a. Reference document: EIA-364-20, *Withstanding Voltage Test Procedure for Electrical Connectors*.
    b. Test Conditions:
        i. Between Adjacent Contacts or Signal-to-Ground
        ii. Rate of Application 500 V/Sec
        iii. Test Voltage (VAC) until breakdown occurs
2) MEASUREMENTS/CALCULATIONS
    a. The breakdown voltage shall be measured and recorded.
    b. The dielectric withstanding voltage shall be recorded as 75% of the minimum breakdown voltage.
    c. The working voltage shall be recorded as one-third (1/3) of the dielectric withstanding voltage (one-fourth of the breakdown voltage)..

TEMPERATURE RISE (Current Carrying Capacity, CCC):

1) EIA-364-70, *Temperature Rise versus Current Test Procedure for Electrical Connectors and Sockets*.
2) When current passes through a contact, the temperature of the contact increases as a result of I^2R (resistive) heating.
3) The number of contacts being investigated plays a significant part in power dissipation and therefore temperature rise.
4) The size of the temperature probe can affect the measured temperature.
5) Copper traces on PC boards will contribute to temperature rise:
    a. Self heating (resistive)
    b. Reduction in heat sink capacity affecting the heated contacts
6) A de-rating curve, usually 20%, is calculated.
7) Calculated de-rated currents at three temperature points are reported:
    a. Ambient
    b. 80^{o} C
    c. 95^{o} C
    d. 115^{o} C
8) Typically, neighboring contacts (in close proximity to maximize heat build up) are energized.
9) The thermocouple (or temperature measuring probe) will be positioned at a location to sense the maximum temperature in the vicinity of the heat generation area.
10) A computer program, *TR 803.exe*, ensures accurate stability for data acquisition.
11) Hook-up wire cross section is larger than the cross section of any connector leads/PC board traces, jumpers, etc.
12) Hook-up wire length is longer than the minimum specified in the referencing standard.

ATTRIBUTE DEFINITIONS

The following is a brief, simplified description of attributes.

LLCR:

1) EIA-364-23, *Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets*.
2) The following guidelines are used to categorize the changes in LLCR as a result from stressing
    a. <= +5.0 mOhms:---------- Stable
    b. +5.1 to +10.0 mOhms: ---------- Minor
    c. +10.1 to +15.0 mOhms: ---------- Acceptable
    d. +15.1 to +50.0 mOhms: ---------- Marginal
    e. +50.1 to +2000 mOhms:---------- Unstable
    f. >+2000 mOhms:---------- Open Failure

RESULTS

Temperature Rise, CCC at a 20% de-rating

- **CCC for a 30°C Temperature Rise ----------5.0 A per contact with 6 contact Powered (ACP Cable Bundle) (Powered the 28 AWG wires at ½ rated current (1.2amp) and monitor the temp rise on the 24 AWG wires)**

Mating&Unmating durability force:

- **Initial**
  - **Mating**
    - **Min ----------1.80 Lbs**
    - **Max----------2.68 Lbs**
  - **Unmating**
    - **Min ----------0.98 Lbs**
    - **Max----------1.42 Lbs**
- **After 25 Cycles**
  - **Mating**
    - **Min ----------1.95 Lbs**
    - **Max----------2.76 Lbs**
  - **Unmating**
    - **Min ----------1.25 Lbs**
    - **Max----------1.84 Lbs**
- **After 50 Cycles**
  - **Mating**
    - **Min ----------1.94 Lbs**
    - **Max----------2.78 Lbs**
  - **Unmating**
    - **Min ----------1.44 Lbs**
    - **Max----------1.95 Lbs**
- **After 75 Cycles**
  - **Mating**
    - **Min ----------2.02 Lbs**
    - **Max----------2.89 Lbs**
  - **Unmating**
    - **Min ----------1.58 Lbs**
    - **Max----------2.22 Lbs**
- **After 100 Cycles**
  - **Mating**
    - **Min ----------2.08 Lbs**
    - **Max----------2.94 Lbs**
  - **Unmating**
    - **Min ----------1.76 Lbs**
    - **Max----------2.47 Lbs**
- **After Humidity**
  - **Mating**
    - **Min ----------1.49 Lbs**
    - **Max----------2.00 Lbs**
  - **Unmating**
    - **Min ----------0.90 Lbs**
    - **Max----------1.17 Lbs**

RESULTS Continued

LLCR Durability (48 LLCR test points, include 16 24 AWG points and 32 28 AWG points)
24 AWG pin:

- **Initial ---------- 22.34 mOhms Max**
- **After 100 Cycles**
  - **<= +5.0 mOhms---------- 16 Points ----------Stable**
  - **+5.1 to +10.0 mOhms ---------- 0 Points ----------Minor**
  - **+10.1 to +15.0 mOhms---------- 0 Points ----------Acceptable**
  - **+15.1 to +50.0 mOhms---------- 0 Points ----------Marginal**
  - **+50.1 to +2000 mOhms---------- 0 Points ----------Unstable**
  - **>+2000 mOhms ---------- 0 Points ----------Open Failure**
- **After thermal shock**
  - **<= +5.0 mOhms---------- 16 Points ----------Stable**
  - **+5.1 to +10.0 mOhms ---------- 0 Points ----------Minor**
  - **+10.1 to +15.0 mOhms---------- 0 Points ----------Acceptable**
  - **+15.1 to +50.0 mOhms---------- 0 Points ----------Marginal**
  - **+50.1 to +2000 mOhms---------- 0 Points ----------Unstable**
  - **>+2000 mOhms ---------- 0 Points ----------Open Failure**
- **After humidity**
  - **<= +5.0 mOhms---------- 14 Points ----------Stable**
  - **+5.1 to +10.0 mOhms ---------- 1 Points ----------Minor**
  - **+10.1 to +15.0 mOhms---------- 1 Points ----------Acceptable**
  - **+15.1 to +50.0 mOhms---------- 0 Points ----------Marginal**
  - **+50.1 to +2000 mOhms---------- 0 Points ----------Unstable**
  - **>+2000 mOhms ---------- 0 Points ----------Open Failure**
  - **>+2000 mOhms ---------- 0 Points ----------Open Failure**

28 AWG pin:

- **Initial ---------- 56.4 mOhms Max**
- **After 100 Cycles**
  - **<= +5.0 mOhms---------- 32 Points ----------Stable**
  - **+5.1 to +10.0 mOhms ---------- 0 Points ----------Minor**
  - **+10.1 to +15.0 mOhms---------- 0 Points ----------Acceptable**
  - **+15.1 to +50.0 mOhms---------- 0 Points ----------Marginal**
  - **+50.1 to +2000 mOhms---------- 0 Points ----------Unstable**
  - **>+2000 mOhms ---------- 0 Points ----------Open Failure**
- **After thermal shock**
  - **<= +5.0 mOhms---------- 31 Points ----------Stable**
  - **+5.1 to +10.0 mOhms ---------- 1 Points ----------Minor**
  - **+10.1 to +15.0 mOhms---------- 0 Points ----------Acceptable**
  - **+15.1 to +50.0 mOhms---------- 0 Points ----------Marginal**
  - **+50.1 to +2000 mOhms---------- 0 Points ----------Unstable**
  - **>+2000 mOhms ---------- 0 Points ----------Open Failure**
- **After humidity**
  - **<= +5.0 mOhms---------- 25 Points ----------Stable**
  - **+5.1 to +10.0 mOhms ---------- 4 Points ----------Minor**
  - **+10.1 to +15.0 mOhms---------- 3 Points ----------Acceptable**
  - **+15.1 to +50.0 mOhms---------- 0 Points ----------Marginal**
  - **+50.1 to +2000 mOhms---------- 0 Points ----------Unstable**
  - **>+2000 mOhms ---------- 0 Points ----------Open Failure**
  - **>+2000 mOhms ---------- 0 Points ----------Open Failure**

RESULTS Continued

Insulation Resistance minimums, IR

Pin-Pin

- **Initial**
  - **Mated ---------- 100000 Meg Ohms ---------- Pass**
  - **Unmated---------- 100000 Meg Ohms ---------- Pass**
- **Thermal**
  - **Mated ---------- 100000 Meg Ohms ---------- Pass**
  - **Unmated---------- 100000 Meg Ohms ---------- Pass**
- **Humidity**
  - **Mated ---------- 100000 Meg Ohms ---------- Pass**
  - **Unmated---------- 100000 Meg Ohms ---------- Pass**

Dielectric Withstanding Voltage minimums, DWV

- **Minimums**
  - **Breakdown Voltage ---------- 1200VAC**
  - **Test Voltage ---------- 900VAC**
  - **Working Voltage ---------- 300VAC**

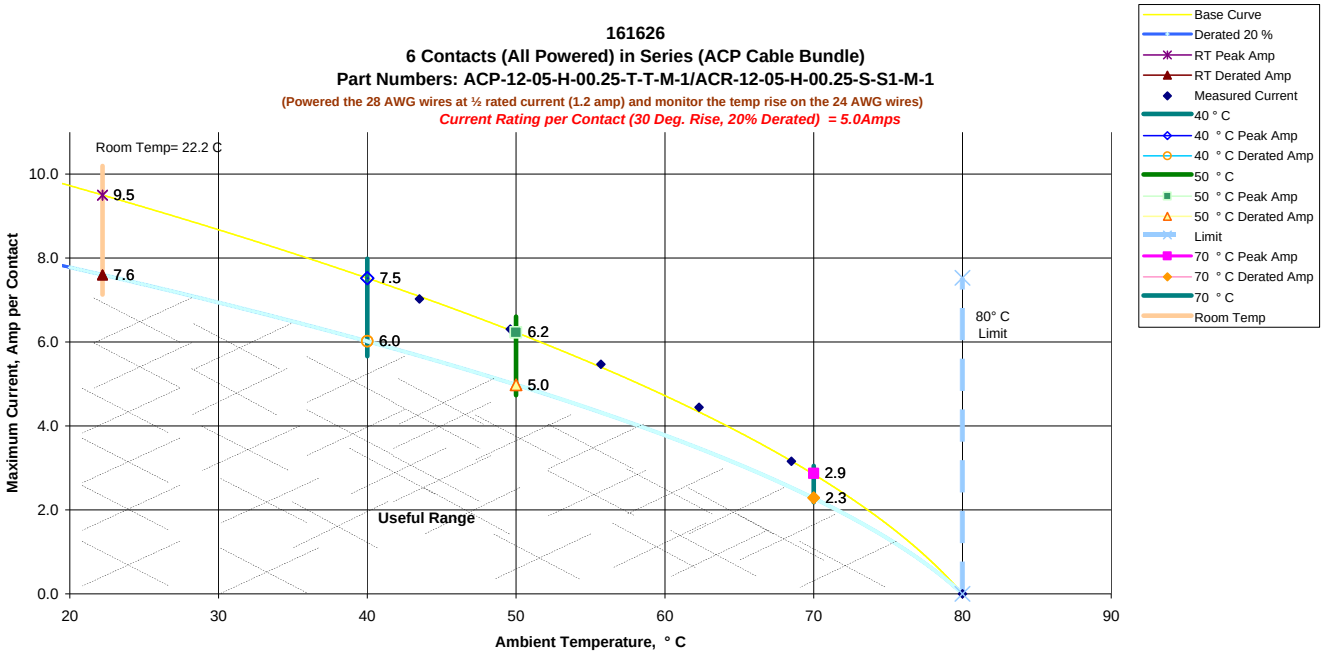
Pin - pin

- **Initial DWV ---------- Passed**
- **Thermal DWV ---------- Passed**
- **Humidity DWV ---------- Passed**

DATA SUMMARIES

TEMPERATURE RISE (Current Carrying Capacity, CCC):

1) High quality thermocouples whose temperature slopes track one another were used for temperature monitoring.
2) The thermocouples were placed at a location to sense the maximum temperature generated during testing.
3) Temperature readings recorded are those for which three successive readings, 15 minutes apart, differ less than 1° C (computer controlled data acquisition).
4) Adjacent contacts were powered:
    a. Linear configuration with 6contact Powered (ACP Cable Bundle contacts)



DATA SUMMARIES Continued

Mating/Unmating durability force:

	Initial				25 Cycles			
	Mating		**Unmating**		**Mating**		**Unmating**	
	Newtons	Force (Lbs)	Newtons	Force (Lbs)	Newtons	Force (Lbs)	Newtons	Force (Lbs)
Minimum	8.01	1.80	4.36	0.98	8.67	1.95	5.56	1.25
Maximum	11.92	2.68	6.32	1.42	12.28	2.76	8.18	1.84
Average	9.51	**2.14**	5.19	**1.17**	10.37	**2.33**	6.63	**1.49**
St Dev	1.43	0.32	0.76	0.17	1.50	0.34	0.77	0.17
Count	8	8	8	8	8	8	8	8

	50 Cycles				75 Cycles			
	Mating		**Unmating**		**Mating**		**Unmating**	
	Newtons	Force (Lbs)	Newtons	Force (Lbs)	Newtons	Force (Lbs)	Newtons	Force (Lbs)
Minimum	8.63	1.94	6.41	1.44	8.98	2.02	7.03	1.58
Maximum	12.37	2.78	8.67	1.95	12.85	2.89	9.87	2.22
Average	10.50	**2.36**	7.50	**1.69**	10.68	**2.40**	8.28	**1.86**
St Dev	1.53	0.34	0.75	0.17	1.43	0.32	0.92	0.21
Count	8	8	8	8	8	8	8	8

	100 Cycles				After Humidity			
	Mating		**Unmating**		**Mating**		**Unmating**	
	Newtons	Force (Lbs)	Newtons	Force (Lbs)	Newtons	Force (Lbs)	Newtons	Force (Lbs)
Minimum	9.25	2.08	7.83	1.76	6.65	1.49	4.01	0.90
Maximum	13.08	2.94	10.99	2.47	8.90	2.00	5.18	1.17
Average	10.86	**2.44**	9.11	**2.05**	7.98	**1.79**	4.74	**1.07**
St Dev	1.35	0.30	1.03	0.23	0.72	0.16	0.37	0.08
Count	8	8	8	8	8	8	8	8

DATA SUMMARIES Continued

INSULATION RESISTANCE (IR):

	Pin to Pin		
	Mated	Unmated	Unmated
Minimum	**ACP/ACR**	**ACP**	**ACR**
Initial	100000	100000	100000
Thermal	100000	100000	100000
Humidity	100000	100000	100000

	Power to Power		
	Mated	Unmated	Unmated
Minimum	**ACP/ACR**	**ACP**	**ACR**
Initial	100000	100000	100000
Thermal	100000	100000	100000
Humidity	100000	100000	100000

	Signal to Power		
	Mated	Unmated	Unmated
Minimum	**ACP/ACR**	**ACP**	**ACR**
Initial	100000	100000	100000
Thermal	100000	100000	100000
Humidity	100000	100000	100000

DATA SUMMARIES Continued

DIELECTRIC WITHSTANDING VOLTAGE (DWV):

Voltage Rating Summary	
Minimum	**ACP/ACR**
Break Down Voltage	1200
Test Voltage	900
Working Voltage	300

Pin to Pin	
Initial Test Voltage	Passed
After Thermal Test Voltage	Passed
After Humidity Test Voltage	Passed

Row to Row	
Initial Test Voltage	Passed
After Thermal Test Voltage	Passed
After Humidity Test Voltage	Passed

Pin to Ground	
Initial Test Voltage	Passed
After Thermal Test Voltage	Passed
After Humidity Test Voltage	Passed

DATA SUMMARIES Continued

LLCR Durabiltiy:

1) A total of 48 points (include 16 24 AWG points and 32 28 AWG points) were measured.
2) EIA-364-23, *Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.*
3) The following guidelines are used to categorize the changes in LLCR as a result from stressing.
   a. <= +5.0 mOhms:---------- Stable
   b. +5.1 to +10.0 mOhms: ---------- Minor
   c. +10.1 to +15.0 mOhms: ---------- Acceptable
   d. +15.1 to +50.0 mOhms: ---------- Marginal
   e. +50.1 to +2000 mOhms---------- Unstable
   f. >+2000 mOhms:---------- Open Failure

24 AWG pin:

Date	9/22/2011	9/22/2011	9/27/2011	10/10/2011
Room Temp C	21	23	22	23
RH	43	41	38	38
Name	Tony Wagoner	Tony Wagoner	Tony Wagoner	Tony Wagoner
mOhm values	**Actual Initial**	**Delta 100 Cycles**	**Delta Thermal**	**Delta Humidity**
Average	21.9	0.2	0.4	1.5
St. Dev.	0.3	0.1	0.4	2.9
Min	21.5	0.0	0.0	0.1
Max	22.3	0.4	1.2	11.2
Count	16	16	16	16

How many samples are being tested?	2
How many contacts are on each board?	8

	Stable	Minor	Acceptable	Marginal	Unstable	Open
100 Cycles	16	0	0	0	0	0
Thermal	16	0	0	0	0	0
Humidity	14	1	1	0	0	0

DATA SUMMARIES Continued

28 AWG pin:

Date	9/22/2011	9/22/2011	9/27/2011	10/10/2011
Room Temp C	21	23	22	23
RH	43	41	38	38
Name	Tony Wagoner	Tony Wagoner	Tony Wagoner	Tony Wagoner
mOhm values	**Actual Initial**	**Delta 100 Cycles**	**Delta Thermal**	**Delta Humidity**
Average	54.1	0.7	1.7	3.6
St. Dev.	0.6	0.4	1.3	3.1
Min	53.2	0.0	0.1	0.1
Max	56.4	1.9	7.3	12.0
Count	32	32	32	32

How many samples are being tested?	2
How many contacts are on each board?	16

	Stable	Minor	Acceptable	Marginal	Unstable	Open
100 Cycles	32	0	0	0	0	0
Thermal	31	1	0	0	0	0
Humidity	25	4	3	0	0	0

EQUIPMENT AND CALIBRATION SCHEDULES

Equipment #: MO-11
Description: Micro-ohmmeter
Manufacturer: Keithley
Model: 3706
Serial #: 120169
Accuracy: Last Cal: 2011-8-21, Next Cal: 2012-8-21

Equipment #: TCT-01
Description: Normal force analyzer
Manufacturer: Mecmesin Multitester
Model: Mecmesin Multitester 2.5-i
Serial #: 08-1049-04
Accuracy: Last Cal: 2012-4-28, Next Cal: 2013-4-27

Equipment #: THC-01
Description: Humidity transmitter
Manufacturer: Thermtron
Model: HMM30C
Serial #: D0240037
Accuracy: Last Cal: 2012-3-3, Next Cal: 2013-3-2

Equipment #: MO-01
Description: Micro-ohmmeter
Manufacturer: Keithley
Model: 2700
Serial #: 1199807
Accuracy: Last Cal: 2012-4-28, Next Cal: 2013-4-27

Equipment #: PS-01
Description: Power Supply
Manufacturer: Agilent
Model: 6031A
Serial #: MY41000982
Accuracy: Last Cal: 2012-4-28, Next Cal: 2013-4-27

Equipment #: TSC-01
Description: Thermal Shock transmitter
Manufacturer: Keithley
Model: 10-VT14994
Serial #: VTS-3-6-6-SC/AC
Accuracy: Last Cal: 2011-11-1, Next Cal: 2012-11-1